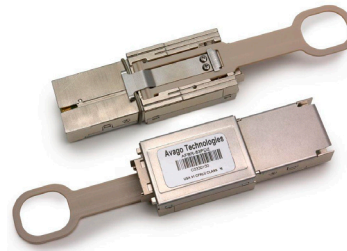


# AFBR-83CDZ

12 Channel × 12.5 Gbps Transceiver  
CXP Pluggable, Parallel Fiber-Optics Module



## Data Sheet



### Description

The Avago Technologies AFBR-83CDZ is a Twelve-Channel, Pluggable, Parallel, Fiber-Optic CXP Transceiver for 12 × 12.5G proprietary application. This transceiver is a high performance module for short-range multi-lane data communication and interconnect applications. It integrates twelve data lanes in each direction with 150 Gbps aggregate bandwidth. Each lane can operate at 12.5 Gbps up to 50 m using OM3 fiber and 65 m using OM4 fiber. These modules are designed to operate over multimode fiber systems using a nominal wavelength of 850 nm. The electrical interface uses an 84-contact edge type connector. The optical interface uses a 24-fiber MTP® (MPO) connector. This module incorporates Avago Technologies proven integrated circuit and VCSEL technology to provide reliable long life, high performance, and consistent service.

### Applications

- 12 × 12.5G proprietary interconnects
- Data Aggregation, Backplane and Proprietary Protocol and Density Applications
- Datacom/Telecom switch & router connections

### Part Number Ordering Options

AFBR-83CDZ	12x 12.5 Gbps with Full Diagnostic Monitoring
AFBR-83EVB	CXP Evaluation Board
AFBR-83EVK*	CXP Evaluation Kit

\* Includes GUI, User Guide, i-Port and Power Supply

### Features

- Compliant to SFF-8642: Mini Multilane Series: Shielded Integrated Connector, and InfiniBand Architecture Specification V2 R1.3 for CXP Interface
- Multi-rate capable from 11 Gbps to 12.5 Gbps
- High Channel Capacity: 150 Gbps per module, bi-directional, with twelve independent Transmitters and Receivers each
- Operates at 12.5 Gbps per channel with 64b/66b encoded data for proprietary application
- Hot Pluggable
- Links up to 50 m using OM3 fiber and 65 m using OM4 fiber
- 0 to 70 °C case temperature operating range
- 3.3 V power supply only
- Low power dissipation of < 3.5 W
- Proven High Reliability 850 nm technology: Avago VCSEL array transmitter and Avago PIN array receiver
- Two Wire Serial (TWS) interface with maskable interrupt for expanded functionality including:
  - Individual channel functions: channel/output disable, squelch disable, and lane polarity inversion
  - Diagnostic Monitoring functions: module temperature and supply voltages, per channel laser current and laser power, and input receiver power
  - Status per channel: Tx fault, electrical (transmitter) and optical (receiver) LOS, and alarm flags
- Utilizes a standard 24 lane optical fiber with MTP® (MPO) optical connector for high density and thin, light-weight cable management

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## WARNING

**INVISIBLE LASER RADIATION  
DO NOT VIEW DIRECTLY  
WITH OPTICAL INSTRUMENTS  
CLASS 1M LASER PRODUCT**

**CAUTION!** Viewing the laser output with certain optical instruments (for example, eye loupes, magnifiers and microscopes) within a distance of 100 mm may pose an eye hazard.

**CAUTION!** Use of controls or adjustments or performance of procedures other than those specified herein may result in hazardous radiation exposure.

Note: Standard used for classification: EN 60825-1:2007

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## CLASS 1M LASER PRODUCT: INVISIBLE LASER RADIATION, DO NOT VIEW DIRECTLY WITH OPTICAL INSTRUMENTS

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### Transmitter

The optical transmitter incorporates a 12-channel VCSEL (Vertical Cavity Surface Emitting Laser) array, a 12-channel input buffer and laser driver, diagnostic monitors, and control and bias blocks. The transmitter is designed for EN 60825 and CDRH eye safety compliance. The Tx Input Buffer provides differential inputs presenting a nominal differential input impedance of 100 Ohms. AC coupling capacitors are located inside the CXP module and are not required on the host board. For module control and interrogation, the control interface incorporates a Two Wire Serial (TWS) interface of clock and data signals.

Modules have monitors for VCSEL bias, light output power (LOP), temperature, and power supply voltage implemented; real-time results are available through the TWS interface. Alarm thresholds are established for the monitored attributes. Flags are set and interrupts generated when the attributes are outside the thresholds.

Over the TWS interface, the user can, for individual channels, control (flip) polarity of the differential inputs, de-activate channels, disable the squelch function and program input equalization levels to reduce the effect of long PCB traces.

Flags are also set and interrupts generated for loss of input signal (LOS) and transmitter fault conditions. All flags are latched and will remain set even if the condition initiating the latch clears and operation resumes. All interrupts can be masked and flags are reset by reading the appropriate flag register.

The optical output will AC squelch for loss of input signal unless squelch is disabled. The input thresholds for the Tx squelch are tied to Tx LOS thresholds which are informative only. See Tx LOS thresholds specification on page 6. Fault detection or channel deactivation through the TWS interface will disable the channel. Status, alarm and fault information are available via the TWS interface. To reduce the need for polling, the hardware interrupt signal is provided to inform hosts of an assertion of an alarm, LOS and/or Tx fault.

### Receiver

The optical receiver incorporates a 12-channel PIN photodiode array, a 12-channel pre-amplifier and output buffer, diagnostic monitors, and control and bias blocks. The Rx Output Buffer provides differential outputs for the high speed electrical interface presenting nominal single-ended output impedances of 50  $\Omega$  to AC ground and 100  $\Omega$  differentially that should be differentially terminated with 100  $\Omega$ . AC coupling capacitors are located inside the CXP module and are not required on the host board.

Modules have a monitor for optical input power; results are available through the TWS interface. Alarm thresholds are established for the monitored attributes. Flags are set and interrupts generated when the attributes are outside the thresholds.

Over the TWS interface, the user can, for individual channels, control (flip) polarity of the differential outputs, de-activate channels, disable the squelch function, program output signal amplitude and deemphasis.

Flags are also set and interrupts generated for loss of optical input signal (LOS). All flags are latched and will remain set even if the condition initiating the latch clears and operation resumes. All interrupts can be masked and flags are reset upon reading the appropriate flag register.

The electrical output will squelch for loss of input signal (unless squelch is disabled) and channel de-activation through TWS interface. Status and alarm information are available via the TWS interface. To reduce the need for polling, the hardware interrupt signal is provided to inform hosts of an assertion of an alarm and/or LOS.

## High Speed Electrical Signal Interface

### TX

TX[0-11]p/n are the CXP module transmitter electrical data inputs and are internally AC coupled (0.1  $\mu$ F) differential lines with 100  $\Omega$  differential terminations. AC coupling capacitors exist inside the CXP module and are not required on the host board. All transmitter electrical input channels are compliant to module CPPI specifications per IEEE 802.3ba other than jitter tolerance performance as per specified in the Transmitter Electrical Characteristics section of this data sheet.

### RX

Rx[0-11]p/n are the CXP module receiver electrical data outputs and are internally AC coupled (0.1  $\mu$ F) differential lines that should be terminated with 100  $\Omega$  differential at the host side. AC coupling capacitors exist inside the CXP module and are not required on the host board. All receiver electrical output channels are compliant to module CPPI specifications per IEEE 802.3ba other than jitter output performance and output differential voltage swing as per specified in the Receiver Electrical Characteristics section of this data sheet.

### Tx Equalization Control

Tx Input Equalization Control: Four bit code blocks (bits 7-4 or 3-0) are assigned to each channel.

- Codes 1xxx<sub>b</sub> are reserved.
- Writing 0111<sub>b</sub> calls for full-scale equalization.
- Writing 0000<sub>b</sub> calls for no equalization.

Intermediate code values call for intermediate levels of equalization.

### Rx De-emphasis Control

Rx Output de-Emphasis Control: Four bit code blocks (bits 7-4 or 3-0) are assigned to each channel.

- Codes 1xxx<sub>b</sub> are reserved.
- Writing 0111<sub>b</sub> calls for full-scale de-emphasis.
- Writing 0000<sub>b</sub> calls for minimum de-emphasis.

Writing intermediate code values calls for intermediate levels of de-emphasis.

## Regulatory & Compliance

Various standard and regulations apply to the modules. These include eye-safety, EMC, ESD and RoHS. See the Regulatory Section for details regarding these and component recognition.

### Handling and Cleaning

The transceiver module can be damaged by exposure to current surges and over voltage events. Care should be taken to restrict exposure to the conditions defined in the Absolute Maximum Ratings. Wave soldering, reflow soldering and/or aqueous wash process with the modules on board are not recommended. Normal handling precautions for electrostatic discharge sensitive devices should be observed.

Each module is supplied with an inserted port plug for protection of the optical ports. This plug should always be in place whenever a fiber cable is not inserted.

The optical connector includes recessed elements that are exposed whenever a cable or port plug is not inserted. Prior to insertion of a fiber optic cable, it is recommended that the cable end be cleaned to avoid contamination from the cable plug. The port plug ensures the optics remains clean and no additional cleaning should be needed. In the event of contamination, dry nitrogen or clean dry air at less than 20 psi can be used to dislodge the contamination. The optical port features (e.g. guide pins) preclude use of a solid instrument. Liquids are also not advised.

## Link Model and Reference Channel

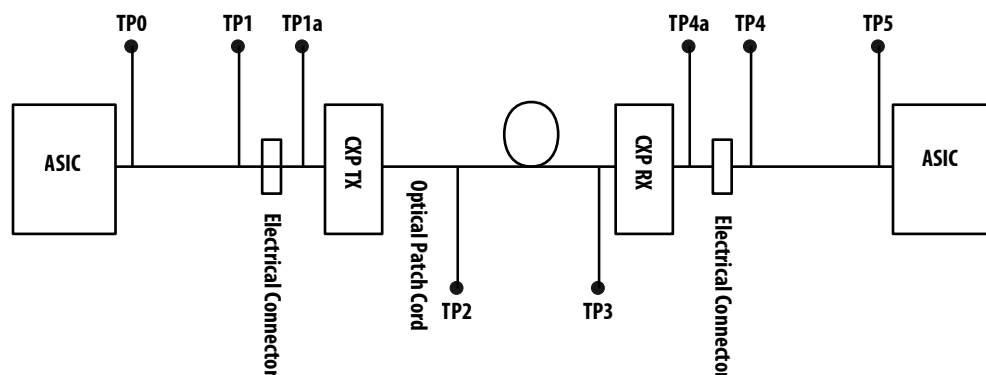


Figure 1. Link Model test point definitions

## Absolute Maximum Ratings

Stress in excess of any of the individual Absolute Maximum Ratings can cause immediate catastrophic damage to the module even if all other parameters are within Recommended Operation Conditions. It should not be assumed that limiting values of more than one parameter can be applied to the module concurrently. Exposure to any of the Absolute Maximum Ratings for extended periods can adversely affect reliability.

Parameter	Symbol	Min	Max	Units	Notes
Storage Temperature	T <sub>s</sub>	-40	85	°C	
Absolute Maximum Operating Temperature			85	°C	Note 1
3.3 V Power Supply Voltage	V <sub>cc33</sub>	-0.5	4.0	V	
Data Input Voltage – Single Ended		-0.5	V <sub>cc33</sub> +0.5, 4.0	V	
Data Input Voltage – Differential	V <sub>dip</sub> - V <sub>din</sub>		1.6	V	Note 2
Control Input Voltage	V <sub>i</sub>	-0.5	V <sub>cc33</sub> +0.5 4.0	V	Note 3
Control Output Current	I <sub>o</sub>	-20	20	mA	
Relative Humidity	RH	5	85	%	
Receiver Damage Threshold			4	dBm	

Notes:

- Electro-optical specifications are not guaranteed outside the recommended operating temperature range. Operation at or above the maximum Absolute Maximum Case Temperature for extended periods may adversely affect reliability.
- This is the maximum voltage that can be applied across the differential inputs without damaging the input circuitry.
- The maximum limit is the lesser of V<sub>cc33</sub> + 0.5 V or 4.0 V

## Recommended Operating Conditions

Recommended Operating Conditions specify parameters for which the electrical characteristics hold unless otherwise noted. Electrical characteristics are not defined for operation outside the Recommended Operating Conditions, reliability is not implied and damage to the module may occur for such operation over an extended period of time.

Parameter	Symbol	Min	Typ	Max	Units	Notes
Case Temperature	Tc	0		70	°C	
3.3 V Power Supply Voltage	Vcc33	3.135	3.3	3.465	V	
Signal Rate per Channel			12.5		GBd	Note 1
Control Input Voltage High	Vih	2.3		3.6	V	
Control Input Voltage Low	Vil	-0.3		0.4	V	
Host Electrical Compliance						Note 2
TJ Jitter output (TP1a)				0.25	UI	
DJ Jitter output (TP1a)				0.15	UI	
RJ Jitter output (TP1a)				0.10	UI	
TJ Jitter tolerance (TP4)		0.75			UI	
DJ Jitter tolerance (TP4)		0.45			UI	
RJ Jitter tolerance (TP4)		0.30			UI	
Fiber Length: 4700 MHz•km 50 μm MMF (OM4)				65	m	Note 3
Fiber Length: 2000 MHz•km 50 μm MMF (OM3)				50	m	
Receiver Differential Data Output Load			100		Ω	

Note:

1. For applications other than 12.5 Gbps per channel, please contact Avago Sales.
2. Per IEEE 802.3ba-2010 TP1a and TP4 CPPI specifications for host except for jitter.
3. 1.5dB allocated for connection and splice loss.

## Transceiver Electrical Characteristics

The following characteristics are defined over the Recommended Operating Conditions unless otherwise noted. Typical values are for Tc = 40°C, Vcc33 = 3.3 V

Parameter	Symbol	Min	Typ	Max	Units	Notes
Transceiver Power Consumption				3.5	W	With module default settings
Transceiver Power Supply Current – Vcc33				1.1	A	With module default settings
Maximum inrush current				1.25	A	On any contact
Maximum current ramp rate				100	mA/μs	
Power Supply Noise including ripple				50	mVpp	Note 1
Power On Initialization Time	t <sub>pwr init</sub>			2000	ms	
Two Wire Serial Interface Clock Rate				400	kHz	
TWS Write Cycle Time (4 byte write)				40	ms	

Note:

1. 1 kHz to frequency of operation at the host supply side of the recommended power supply filter with the module and recommended filter in place. See Figure 9 for recommended power supply filter.

## Transmitter Electrical Characteristics

The following characteristics are defined over the Recommended Operating Conditions unless otherwise noted. Typical values are for  $T_c = 40^\circ\text{C}$ ,  $V_{cc33} = 3.3\text{ V}$

Parameter	Symbol	Min	Typ	Max	Units	Notes
Differential Input Impedance		80	100	120	$\Omega$	
LOS Assert Threshold: Tx Data Input Differential Peak-to-Peak Voltage Swing	$\Delta V_{di\ pp\ losA}$		110		mVpp	Note 1 Informative
LOS De-Assert Threshold: Tx Data Input Differential Peak-to-Peak Voltage Swing	$\Delta V_{di\ pp\ losD}$		130	210	mVpp	Note 1 Informative
LOS Hysteresis		0.5		4	dB	

Parameter	Test Point	Min	Typ	Max	Units	Notes/Conditions
Single ended input voltage tolerance	TP1a	-0.3		4.0	V	Note 2
AC common mode input voltage tolerance	TP1a	15			mV	RMS
Differential input return loss	TP1		footnote		dB	10 MHz to 11.1 GHz Note 3
Differential to common-mode input return loss	TP1	10			dB	10 MHz to 11.1 GHz
TJ Jitter tolerance	TP1a	0.25			UI	
DJ Jitter tolerance	TP1a	0.15			UI	
RJ Jitter tolerance	TP1a	0.10			UI	
Data Dependent Pulse Width Shrinkage (DDPWS) tolerance	TP1a	0.07			UI	
Eye Mask Coordinates: X1, X2, Y1, Y2	TP1a	SPECIFICATION VALUES				Hit Ratio = $5 \times 10^{-5}$
			0.11, 0.31		UI	
			95, 350		mV	

Notes:

- At default Tx EQ setting only. Informative only. Tx LOS thresholds also represent the Tx channel squelch thresholds when enabled. Behavior per IBTA Annex A6 CXP Interface Specification (Tx squelch disabled).
- Referred to TP1 signal common; The single-ended input voltage tolerance is the allowable range of the instantaneous input signals
- From 10 MHz to 11.1 GHz, the magnitude in decibels of the module differential input return loss at TP1 and the host differential output return loss at TP1a shall not exceed the limit given in Equation

$$\begin{aligned} \text{Return\_loss}(f) &\geq 12 - 2\sqrt{f} && 0.01 \leq f < 4.1 \text{ GHz} \\ &\geq 6.3 - 13\log_{10}\left(\frac{f}{5.5}\right) && 4.11 \leq f < 11.1 \text{ GHz} \end{aligned}$$

$\text{Return\_loss}(f)$  is the return loss at frequency  $f$   
 $f$  is the frequency in GHz.

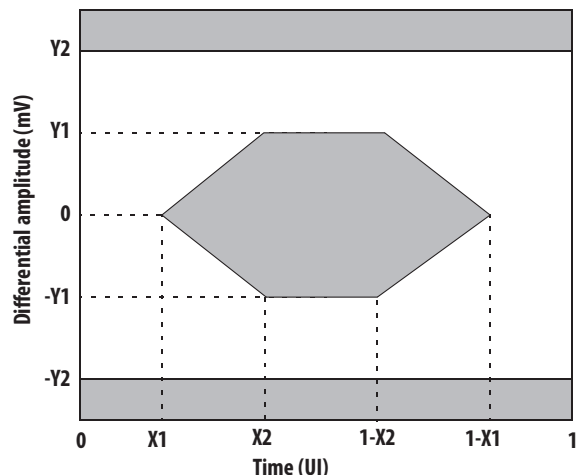


Figure 2. Tx Electrical Eye Mask Coordinates (TP1a) at Hit ratio  $5 \times 10^{-5}$  hits per sample

## Receiver Electrical Characteristics

The following characteristics are defined over the Recommended Operating Conditions, with module default settings, unless otherwise noted. Typical values are for  $T_c = 40^\circ\text{C}$ ,  $V_{cc33} = 3.3\text{ V}$

Parameter	Test Point	Min	Typ	Max	Units	Notes/Conditions
Data Output Differential Peak-to-Peak Voltage Swing	TP4	220		850	mV	
AC common mode voltage (RMS)	TP4			7.5	mV	RMS
Termination mismatch at 1MHz	TP4			5	%	
Differential output return loss	TP4		footnote			10 MHz to 11.1 GHz Note 1
Common-mode output return loss	TP4		footnote			10 MHz to 11.1 GHz Note 2
Output transition time 20% to 80%	TP4	28			ps	
TJ Jitter output	TP4			0.75	UI	
DJ Jitter output	TP4			0.45	UI	
RJ Jitter output	TP4			0.30	UI	
Data Dependent Pulse Width Shrinkage (DDPWS)	TP4			0.34	UI	
Eye Mask coordinates: X1, X2, Y1, Y2	TP4	SPECIFICATION VALUES				Hit Ratio = $5 \times 10^{-5}$
			0.29, 0.5		UI	
			110, 425		mV	

Notes:

- From 10 MHz to 11.1 GHz, the magnitude in decibels of the module differential output return loss at TP4 and the host differential input return loss at TP4a shall not exceed the limit given in Equation

$$\begin{aligned} \text{Return\_loss}(f) &\geq 12 - 2\sqrt{f} && 0.01 \leq f < 4.1 \text{ GHz} \\ &\geq 6.3 - 13\log_{10}\left(\frac{f}{5.5}\right) && 4.11 \leq f < 11.1 \text{ GHz} \end{aligned}$$

- From 10 MHz to 11.1 GHz, the magnitude in decibels of the module common-mode output return loss at TP4 shall not exceed the limit given in Equation

$$\begin{aligned} \text{Return\_loss}(f) &\geq 7 - 1.6f && 0.01 \leq f < 2.5 \text{ GHz} \\ &\geq 3 && 2.5 \leq f < 11.1 \text{ GHz} \end{aligned}$$

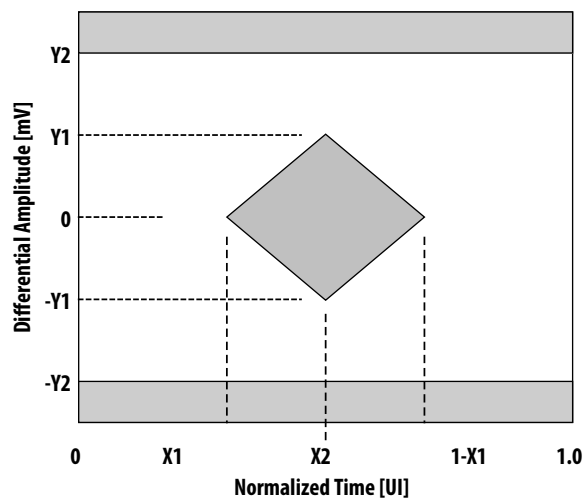


Figure 3. Rx Electrical Eye Mask Coordinates (TP4) at Hit ratio  $5 \times 10^{-5}$  hits per sample

## Transmitter Optical Characteristics

The following characteristics are defined over the Recommended Operating Conditions unless otherwise noted. Typical values are for  $T_c = 40^\circ\text{C}$ ,  $V_{cc33} = 3.3\text{ V}$

Parameter	Test Point	Min	Typ	Max	Units	Notes/Conditions
Center wavelength	TP2	840	850	860	nm	
RMS spectral width	TP2			0.65	nm	RMS Spectral Width is the standard deviation of the spectrum
Average launch power, each lane	TP2	-7.6		2.4	dBm	
Optical Modulation Amplitude (OMA) each lane	TP2	-5.6		3	dBm	Even if the TDP < 0.9 dB, the OMA minimum must exceed this minimum value
Difference in launch power between any two lanes (OMA)	TP2			4	dB	
Peak power, each lane	TP2			4	dBm	
Launch power in OMA minus TDP, each lane	TP2	-6.5			dBm	
Transmitter and dispersion penalty (TDP), each lane	TP2			3.5	dB	
Extinction ratio	TP2	3			dB	
Optical return loss tolerance	TP2			12	dB	
Encircled flux	TP2	$\geq 86\%$ at $19\ \mu\text{m}$ , $\leq 30\%$ at $4.5\ \mu\text{m}$				If measured into type A1a.2 $50\ \mu\text{m}$ fiber in accordance with EN 61280-1-4
Eye Mask coordinates: X1, X2, X3, Y1, Y2, Y3	TP2	SPECIFICATION VALUES 0.23, 0.34, 0.43, 0.27, 0.35, 0.4			UI	Hit Ratio = $5 \times 10^{-5}$
Average launch power of OFF transmitter, each lane	TP2			-30	dBm	

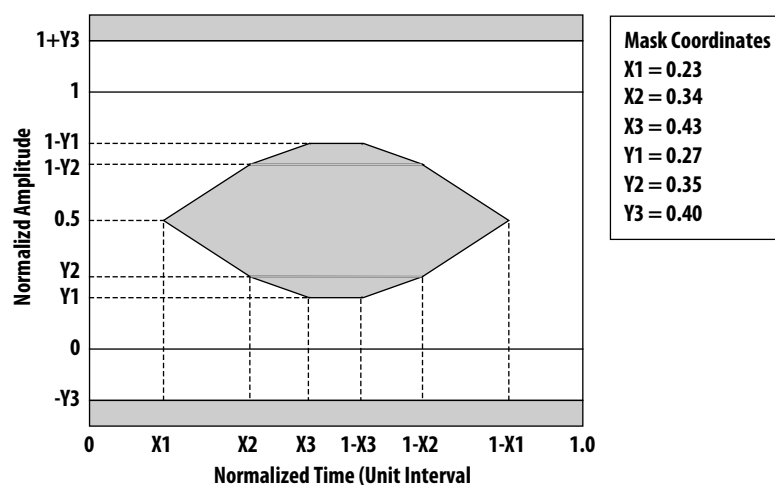


Figure 4. Transmitter eye mask definitions (TP2) at Hit ratio  $5 \times 10^{-5}$  hits per sample



## Receiver Optical Characteristics

The following characteristics are defined over the Recommended Operating Conditions unless otherwise noted. Typical values are for  $T_c = 40^\circ\text{C}$ ,  $V_{cc33} = 3.3\text{ V}$

Parameter	Test Point	Min	Typ	Max	Units	Notes/Conditions
Center wavelength, each lane	TP3	840	850	860	nm	
Damage Threshold	TP3	3.4			dBm	Note 1
Average power at receiver input, each lane	TP3	-9.5		2.4	dBm	
Receiver Reflectance	TP3			-12	dB	
Optical Modulation Amplitude (OMA), each lane	TP3	-7.5		3	dBm	
Stressed receiver sensitivity in OMA, each lane	TP3			-5.4	dBm	Measured with conformance test signal at TP3 for BER = $10e-12$
Peak power, each lane	TP3			4	dBm	
Conditions of stressed receiver sensitivity:	TP3					Note 2
Vertical Eye Closure Penalty, each lane	TP3		3.5		dB	
Stressed eye J2, Jitter, each lane	TP3		0.30		UI	
Stressed eye J9, Jitter, each lane	TP3		0.47		UI	
OMA of each aggressor lane	TP3		-0.4		dBm	
Rx LOS Assert Threshold	TP3	-30			dBm OMA	
Rx LOS De-assert Threshold	TP3			-8	dBm OMA	
LOS Hysteresis	TP3	0.5			dB	

Notes:

1. The receiver shall be able to tolerate, without damage, continuous exposure to a modulated optical input signal having this power level on one lane. The receiver does not have to operate correctly at this input power
2. Vertical eye closure penalty and stressed eye jitter are test conditions for measuring stressed receiver sensitivity. They are not characteristics of the receiver. The apparent discrepancy between VECP and TDP is because VECP is defined at eye center while TDP is defined with  $\pm 0.15$  UI offsets of the sampling instant

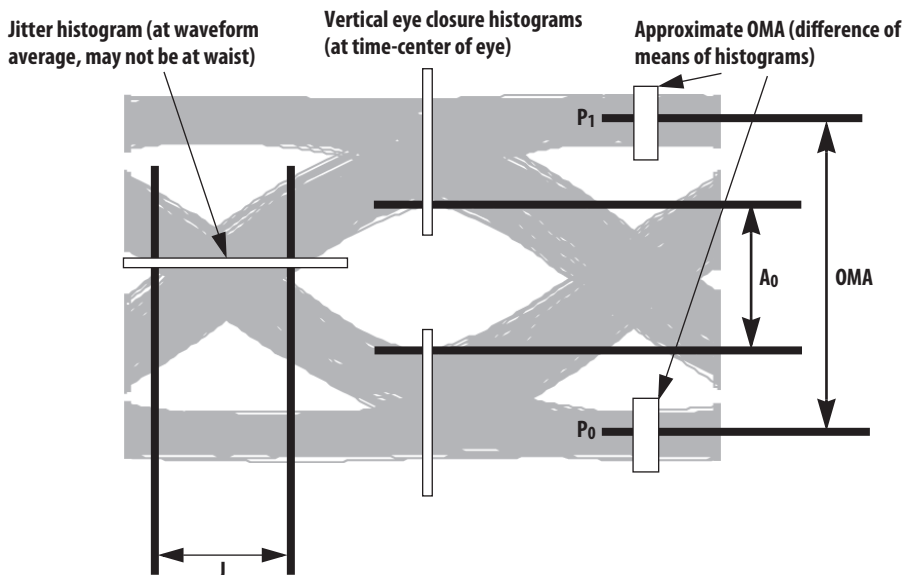


Figure 5. Required characteristics of the conformance test signal at TP3 – definitions of the conditions of stressed receiver sensitivity

## Regulatory and Compliance

Feature	Test Method	Performance
Electrostatic Discharge (ESD) to the Electrical Contacts	JEDEC Human Body Model (HBM) (JESD22-A114-B)	High speed signal contacts shall withstand 1000 V. All other contacts shall withstand 2000 V
Electrostatic Discharge (ESD) to Optical Connector Receptacle	EN 61000-4-2, criterion B	When installed in a properly grounded housing and chassis the units are subjected to 15 KV air discharges during operation and 8 KV direct contact discharges to the case
Electromagnetic Interference (EMI)	FCC Part 15 CENELEC EN55022 (CISPR 22A) VCCI Class 1	Typically passes with 10 dB margin. Actual performance dependent on enclosure design
Immunity	Variation of EN 61000-4-3	Typically minimum effect from a 10 V/m field swept from 80 MHz to 1 GHz applied to the module without a chassis enclosure
Laser Eye Safety and Equipment Type Testing	EN 60950-1:2006+A11+A1+A12 EN 60825-1:2007 EN 60825-2:2004+A1+A2	P <sub>out</sub> : EN AEL & US FDA CDRH Class 1M TUV File Number: R72122669
Component Recognition	Underwriters Laboratories and Canadian Standards Association Joint Component Recognition for Information Technology Equipment including Electrical Business Equipment	UL File Number: E173874
RoHS Compliance	BS EN 1122:2001 Mtd B by ICP for Cadmium, EPA Method 3051A by ICP for Lead and Mercury, EPA Method 3060A & 7196A by UV/Vis Spectrophotometry for Hexavalent Chromium. EPA Method 3540C/3550B by GC/MS for PPB and PBDE  BS EN method by ICP and EPA methods by ICP, UV/Vis Spectrophotometry and GC/MS.	Less than 100 ppm of cadmium, Less than 1000 ppm of lead, mercury, hexavalent chromium, polybrominated biphenyls, and polybrominated biphenyl esters.

## Pin Assignment

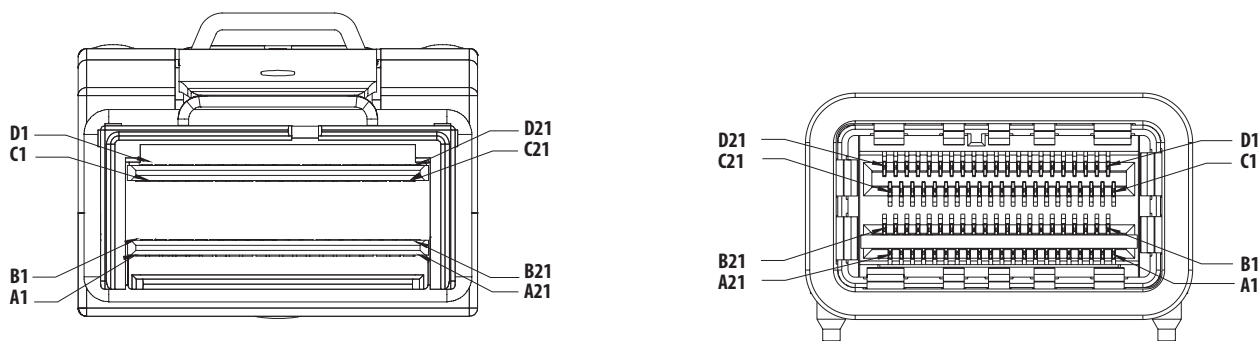


Figure 6. CXP module and host board connector pin assignments

## Transceiver Contact Assignment and Signal Description

There are 21 pads per level, for a total of 84, with 48 pads allocated for (12+12) differential pairs, 28 for Signal Common or Ground (GND), 4 for power connections, 4 for control/service.

Bottom side			Top Side		
I/O #	Name	Contact Length	Contact Length	Name	I/O #
<b>Receiver -- Top Card</b>					
C1	GND			GND	D1
C2	Rx1p			Rx0p	D2
C3	Rx1n			Rx0n	D3
C4	GND			GND	D4
C5	Rx3p			Rx2p	D5
C6	Rx3n			Rx2n	D6
C7	GND			GND	D7
C8	Rx5p			Rx4p	D8
C9	Rx5n			Rx4n	D9
C10	GND			GND	D10
C11	Rx7p			Rx6p	D11
C12	Rx7n			Rx6n	D12
C13	GND			GND	D13
C14	Rx9p			Rx8p	D14
C15	Rx9n			Rx8n	D15
C16	GND			GND	D16
C17	Rx11p			Rx10p	D17
C18	Rx11n			Rx10n	D18
C19	GND			GND	D19
C20	PRSNT_L			Vcc3.3-Rx	D20
C21	Int_L/Reset_L			Not used	D21

**Transmitter -- Bottom Card**

A1	GND			GND	B1
A2	Tx1p			Tx0p	B2
A3	Tx1n			Tx0n	B3
A4	GND			GND	B4
A5	Tx3p			Tx2p	B5
A6	Tx3n			Tx2n	B6
A7	GND			GND	B7
A8	Tx5p			Tx4p	B8
A9	Tx5n			Tx4n	B9
A10	GND			GND	B10
A11	Tx7p			Tx6p	B11
A12	Tx7n			Tx6n	B12
A13	GND			GND	B13
A14	Tx9p			Tx8p	B14
A15	Tx9n			Tx8n	B15
A16	GND			GND	B16
A17	Tx11p			Tx10p	B17
A18	Tx11n			Tx10n	B18
A19	GND			GND	B19
A20	SCL			Vcc3.3-Tx	B20
A21	SDA			Not used	B21

Pin	Signal Name	Signal Description	Logic	Notes
A1	GND	Ground		
A2	TX1p	Transmitter Non-Inverted Data Input	CML-I	
A3	TX1n	Transmitter Inverted Data Input	CML-I	
A4	GND	Ground		
A5	TX3p	Transmitter Non-Inverted Data Input	CML-I	
A6	TX3n	Transmitter Inverted Data Input	CML-I	
A7	GND	Ground		
A8	TX5p	Transmitter Non-Inverted Data Input	CML-I	
A9	TX5n	Transmitter Inverted Data Input	CML-I	
A10	GND	Ground		
A11	TX7p	Transmitter Non-Inverted Data Input	CML-I	
A12	TX7n	Transmitter Inverted Data Input	CML-I	
A13	GND	Ground		
A14	TX9p	Transmitter Non-Inverted Data Input	CML-I	
A15	TX9n	Transmitter Inverted Data Input	CML-I	
A16	GND	Ground		
A17	TX11p	Transmitter Non-Inverted Data Input	CML-I	
A18	TX11n	Transmitter Inverted Data Input	CML-I	
A19	GND	Ground		
A20	SCL	Two-wire serial interface clock	LVC MOS-I/O	1
A21	SDA	Two-wire serial interface data	LVC MOS-I/O	1
B1	GND	Ground		
B2	TX0p	Transmitter Non-Inverted Data Input	CML-I	
B3	TX0n	Transmitter Inverted Data Input	CML-I	
B4	GND	Ground		
B5	TX2p	Transmitter Non-Inverted Data Input	CML-I	
B6	TX2n	Transmitter Inverted Data Input	CML-I	
B7	GND	Ground		
B8	TX4p	Transmitter Non-Inverted Data Input	CML-I	
B9	TX4n	Transmitter Inverted Data Input	CML-I	
B10	GND	Ground		
B11	TX6p	Transmitter Non-Inverted Data Input	CML-I	
B12	TX6n	Transmitter Inverted Data Input	CML-I	
B13	GND	Ground		
B14	TX8p	Transmitter Non-Inverted Data Input	CML-I	
B15	TX8n	Transmitter Inverted Data Input	CML-I	
B16	GND	Ground		
B17	TX10p	Transmitter Non-Inverted Data Input	CML-I	
B18	TX10n	Transmitter Inverted Data Input	CML-I	
B19	GND	Ground		
B20	VCC3.3-TX	+3.3 V Power supply Transmitter		
B21	Not used	Not used , 3.3 V only		

Note:

1. Host shall use a pull up of 1.5 kohm – 10 kohm to Vcc3.3.

Pin	Signal Name	Signal Description	Logic	Notes
C1	GND	Ground		
C2	RX1p	Receiver Non-Inverted Data Output	CML-O	
C3	RX1n	Receiver Inverted Data Output	CML-O	
C4	GND	Ground		
C5	RX3p	Receiver Non-Inverted Data Output	CML-O	
C6	RX3n	Receiver Inverted Data Output	CML-O	
C7	GND	Ground		
C8	RX5p	Receiver Non-Inverted Data Output	CML-O	
C9	RX5n	Receiver Inverted Data Output	CML-O	
C10	GND	Ground		
C11	RX7p	Receiver Non-Inverted Data Output	CML-O	
C12	RX7n	Receiver Inverted Data Output	CML-O	
C13	GND	Ground		
C14	RX9p	Receiver Non-Inverted Data Output	CML-O	
C15	RX9n	Receiver Inverted Data Output	CML-O	
C16	GND	Ground		
C17	RX11p	Receiver Non-Inverted Data Output	CML-O	
C18	RX11n	Receiver Inverted Data Output	CML-O	
C19	GND	Ground		
C20	PRSNT_L	Module Present	O	1
C21	Int_L/Reset_L	Interrupt / Reset	I/O	2
D1	GND	Ground		
D2	RX0p	Receiver Non-Inverted Data Output	CML-O	
D3	RX0n	Receiver Inverted Data Output	CML-O	
D4	GND	Ground		
D5	RX2p	Receiver Non-Inverted Data Output	CML-O	
D6	RX2n	Receiver Inverted Data Output	CML-O	
D7	GND	Ground		
D8	RX4p	Receiver Non-Inverted Data Output	CML-O	
D9	RX4n	Receiver Inverted Data Output	CML-O	
D10	GND	Ground		
D11	RX6p	Receiver Non-Inverted Data Output	CML-O	
D12	RX6n	Receiver Inverted Data Output	CML-O	
D13	GND	Ground		
D14	RX8p	Receiver Non-Inverted Data Output	CML-O	
D15	RX8n	Receiver Inverted Data Output	CML-O	
D16	GND	Ground		
D17	RX10p	Receiver Non-Inverted Data Output	CML-O	
D18	RX10n	Receiver Inverted Data Output	CML-O	
D19	GND	Ground		
D20	VCC3.3-RX	+3.3 V Power supply receiver		
D21	Not used	Not used , 3.3 V only		

Notes:

1. Shorted directly to GND inside the module.
2. Int\_L/Reset\_L is a bidirectional contact. When driven from the host, it operates logically as a Reset signal (input). When driven from the module, it operates logically as an Interrupt signal (output). Signal levels are per specified in Low Speed Logic section. Host shall use a pull up of 1.5 kohm – 10 kohm to Vcc3.3 for this pin.

## Control Interface

The control interface includes a bi-directional Int\_L/Reset\_L interrupt/reset signal and two-wire serial – SCL (clock) and SDA (data) signals to provide users rich functionality over an efficient and easily used interface. The TWS interface is implemented as a slave device and compatible with industry standard two-wire serial protocol. Signal and timing characteristics are further defined in this section. In general, TWS bus timing and protocols follow the implementation popularized in Atmel Two-wire Serial EEPROMs.

## Low-Speed Electrical Contact Definitions

### SDA, SCL

SCL is the clock of the two-wire serial interface, and SDA is the data for the two-wire interface. SCL and SDA must be pulled up in the host through a pull-up resistor of value appropriate to the overall bus capacitance and the rise and fall time requirements as per “CXP two-wire Serial Interface Timing Specifications” table.

The host supplied SCL input to the CXP transceiver is used to positive-edge clock data into each CXP device and negative-edge clock data out of each device. CXP transceivers operate only as slave devices. The host must provide a bus master for SCL and initiate all read/write communication.

Since all CXP transceivers use the same two base addresses, each CXP port requires its own SCL/SDA bus. Support of multiple ports in a host requires multiple SCL/SDA buses, or multiplexing circuitry such as a multiplexer chip or a switch chip.

### INT\_L/RESET\_L

Int\_L/Reset\_L is a bidirectional contact. When driven from the host, it operates logically as a Reset signal. When driven from the module, it operates logically as an Interrupt signal. In both cases, the signal is asserted low, as indicated by the ‘\_L’ suffix. The Int\_L/Reset\_L signal requires open collector outputs in both the host and the module, and must be pulled up on the host board with 1.5 kohm – 10 kohm resistor. The two uses are distinguished by timing – a shorter assertion, driven by the module indicates an interrupt and a longer assertion of the signal driven by the host indicates a reset as per “I/O Timing for Control and Status Functions” Table below.

### Int\_L operation:

When Int\_L/Reset\_L is pulled “Low” by the module for longer than the minimum pulse width ( $t_{Int\_L, PW-min}$ ) and shorter than the maximum pulse width ( $t_{Int\_L, PW-max}$ ) the signal signifies an interrupt. When asserted “Low”, Int\_L indicates a possible module operational fault or a status critical to the host system. The host identifies the cause of the interrupt using the two-wire serial interface. Int\_L must operate in Pulse mode (as opposed to Static mode), in order to distinguish a short Int\_L signal from a longer Reset\_L signal, so the module must de-assert Int\_L/Reset\_L after the interrupt has been signaled.

### Reset\_L operation:

When the Int\_L/Reset\_L signal is pulled “Low” by the host for longer than the minimum reset pulse length ( $t_{Reset\_L, PW-min}$ ), it initiates a complete module reset, returning all user module settings to their default state. There is no maximum reset pulse length. Module Reset Assert Time ( $t_{init}$ ) starts on the rising edge after the low level on the Reset\_L signal is released. During the execution of a reset ( $t_{init}$ ) the host shall disregard all status bits until the module indicates a completion of the reset interrupt. The module indicates this by posting an Int\_L signal with the Data\_Not\_Ready bit (Memory Map, Byte 2, bit 0) negated. Note that on power up (including hot insertion) the module will post this completion of reset interrupt without requiring a reset from the host.

### PRSNT\_L

PRSNT\_L is used to indicate when the module is plugged into the host receptacle. PRSNT\_L is pulled up to Vcc3.3 on the host board through > 50 k $\Omega$  and pulled down directly to signal common (no resistor) in the module. The PRSNT\_L is asserted “Low” when inserted and deasserted “High” when the module is physically absent from the host connector.

## I/O Timing for Control and Status Functions

Parameter	Symbol	Min	Max	Unit	Condition, and Notes
Initialization Time	$t_{init}$		2000	ms	Note 1 2, 3
Reset Pulse Width - Min.	$t_{reset\_L,PW-min}$	25		ms	Note 4
Monitor Data Ready Time	$t_{data}$		2000	ms	Note 5
Reset Assert Time	$t_{RSTL,OFF}$		2000	ms	Note 6
Int_L Assert Time	$t_{Int\_L,ON}$		200	ms	Note 7
Interrupt Pulse Width - Min	$t_{Int\_L,PW-min}$	5		$\mu$ s	Note 8
Interrupt Pulse Width - Max	$t_{Int\_L,PW-max}$		50	$\mu$ s	Note 9
Int_L Deassert Time	$t_{Int\_L,OFF}$		100	ms	Note 10
Rx LOS Assert Time	$t_{LOS,ON}$		100	ms	Note 11
Tx Fault Assert Time	$t_{Txfault,ON}$		200	ms	Note 12
Flag Assert Time	$t_{flag,ON}$		200	ms	Note 13
Mask Assert Time	$t_{mask,OFF}$		100	ms	Note 14
Mask Deassert Time	$t_{mask,ON}$		100	ms	Note 15
Select Change Time	$t_{ratesel}$		100	ms	Note 16

### Notes:

1. Time from power on, hot plug or rising edge of reset until the module is fully functional.
2. Power on is defined as the instant when supply voltages reach and remain at or above the minimum level as specified in the power supply specifications.
3. Fully functional is defined as Int\_L asserted due to Data Not Ready (Byte 2, bit 0) deasserted. The module should meet the optical and electrical specifications.
4. This is the minimum Reset\_L pulse width required to reset a module. Assertion of Reset\_L activates a complete module reset, i.e. module returns to the factory default control settings. While Reset\_L is low, the Tx and Rx outputs are disabled and the module does not response to the 2WS serial interface.
5. Time from power on to Data Not Ready (Byte 2, bit 0) deasserted and Int\_L asserted.
6. Time from rising edge on the Reset\_L contact until the module is fully functional. During the Reset Time module will not respond to a "low" on the Int\_L/Reset\_L signal.
7. Time from occurrence of condition triggering Int\_L until  $V_{out}:Int\_L = V_{ol}$ .
8. Int\_L operates in pulse mode. Static mode (Int\_L stays low until reset by host) is not supported for Int\_L.
9. Int\_L pulse width must not exceed  $t_{Int\_L,PW-max}$  to distinguish Int\_L from a Reset for other devices on bus.
10. Time from clear on read operation of associated flag until Int\_L Status (Lower page, byte 2, bit 1) is cleared. This includes deassert times for Rx LOS, Tx Fault and other flag bit. Measured from falling clock edge after stop bit of read transaction.
11. Time from Rx LOS state to Rx LOS bit set (value = 1b) and Int\_L asserted.
12. Time from Tx Fault state to Tx Fault bit set (value = 1b) and Int\_L asserted.
13. Time from occurrence of condition triggering flag to associated flag bit set (value = 1b) and Int\_L asserted.
14. Time from mask bit set (value = 1b) until associated Int\_L assertion is inhibited.
15. Time from mask bit cleared (value = 0b) until associated Int\_L operation resumes.
16. Time from change of state of Application or Rate Select bit until transmitter or receiver bandwidth is in conformance with appropriate specification.

## Low Speed Logic

Management signaling logic levels are based on Low Voltage CMOS operating at 3.3 V  $V_{CC}$ . Host shall use a pull-up (1.5 kohm – 10 kohm) to  $V_{CC3.3}$  for the Two-wire interface SCL (clock), SDA (address & data), and Int\_L/Reset\_L signals.

### Low Speed Control and Sense Signal Specifications

Parameter	Symbol	Min	Max	Units	Condition
Module Input Voltage Low	$V_{il}$	-0.3	0.4	V	Pull-up to 3.3V.
Module Input Voltage High	$V_{ih}$	2.3	3.6	V	Min $V_{ih} = 0.7 \cdot 3.3V$ .
Module Output Voltage Low	$V_{ol}$	-0.3	0.3	V	Condition $I_{OL} = 3.0$ mA. Pull-up to 3.3V.
Module Output Voltage High	$V_{oh}$	2.8	3.6	V	Min $V_{oh} = 3.3V - 0.5V$ .
Module Output Current High	$I_{oh}$	-10	10	$\mu A$	$-0.3 V < V_{output} < 3.6 V$
Capacitance of module on SCL, SDA and Int_L/Reset_L I/O contacts	$C_{i,SCLSDA}$		36	pF	Allocate 28 pF for IC, 8 pF for module PCB
Capacitance of module on Int_L/Reset_L I/O contact	$C_{i,INT\_L}$		36	pF	Allocate 28 pF for IC, 8 pF for module PCB
Total bus capacitive load, SCL, SDA and Int_L/Reset_L I/O pin	$C_b$		100	pF	3.0 k $\Omega$ Pullup resistor, max
			200	pF	1.6 k $\Omega$ Pullup resistor, max

### Management Interface Timing Specification

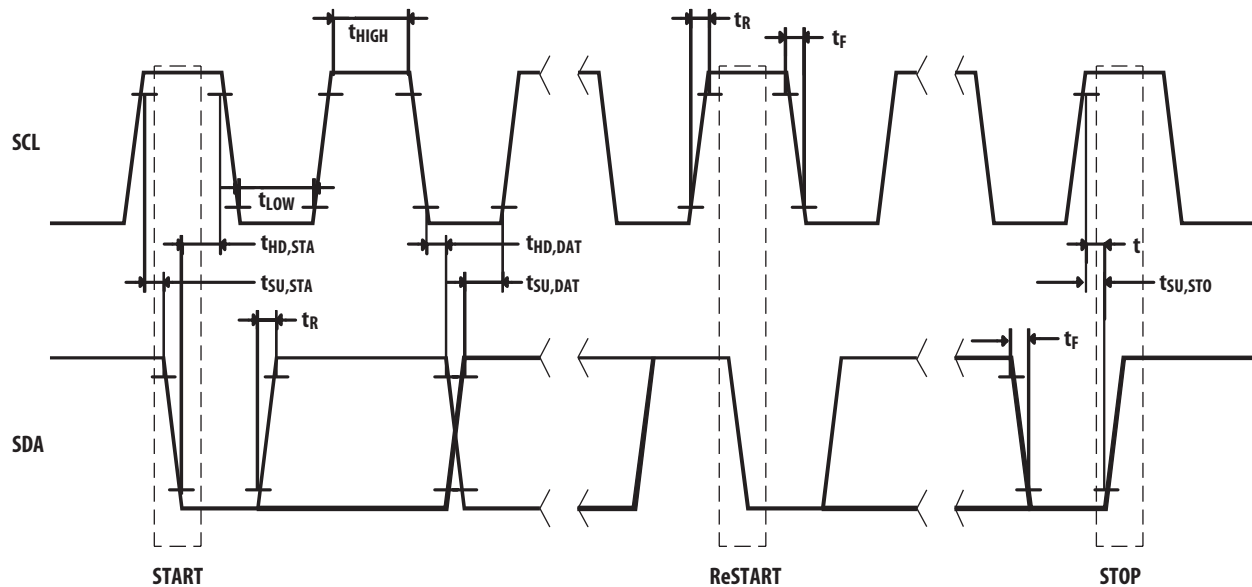


Figure 7. Two-wire Serial Interface Timing Diagram



## CXP Two-Wire Serial Interface Timing Specifications

Parameter	Symbol	Min	Max	Unit	Condition
Clock Frequency	$f_{SCL}$	0	400	kHz	
Clock Pulse Width Low	$t_{LOW}$	1.3		$\mu s$	
Clock Pulse Width High	$t_{HIGH}$	0.6		$\mu s$	
Time bus free before new transmission can start	$t_{BUF}$	20		$\mu s$	Note 1
START Set-up Time	$t_{SU,STA}$	0.6		$\mu s$	
START Hold Time	$t_{HD,STA}$	0.6		$\mu s$	
Data Set-up Time	$t_{SU,DAT}$	0.1		$\mu s$	Note 2
Data Hold Time	$t_{HD,DAT}$	0		$\mu s$	Note 3
SDA and SCL rise time	$t_{R,400}$		0.3	$\mu s$	Note 4
SDA and SCL fall time	$t_{F,400}$		0.3	$\mu s$	Note 5
STOP Set-up Time	$t_{SU,STO}$	0.6		$\mu s$	

Notes:

1. Between STOP & START and between ACK & ReSTART.
2. Data In Set Up Time is measured from  $V_{il(max)SDA}$  or  $V_{ih(min)SDA}$  to  $V_{il(max)SCL}$ .
3. Data In Hold Time is measured from  $V_{il(max)SCL}$  to  $V_{il(max)SDA}$  or  $V_{ih(min)SDA}$ .
4. Rise Time is measured from  $V_{ol(max)SDA}$  to  $V_{oh(min)SDA}$ .
5. Fall Time is measured from  $V_{oh(min)SDA}$  to  $V_{ol(max)SDA}$ .

## Memory Specifications

Memory may be accessed in single-byte or multi-byte (up to 4 bytes) memory blocks. The largest multiple-byte contiguous write operation that a module shall handle is 4 bytes. The minimum size write block is 1 byte.

### Memory Transaction Timing Specification

Parameter	Symbol	Min	Max	Unit	Condition
Serial Interface Clock Holdoff - "Clock Stretching"	$T_{clock\_hold}$		500	$\mu s$	Note 1
Complete Single or Sequential Write	$t_{WR}$		40	ms	Note 2
Endurance (Write cycles)		50,000	75,000	cycles	Note 3

Notes:

1. Maximum time the CXP module may hold the SCL line low before continuing with a read or write operation.
2. Complete up to 4 Byte write. Timing should start from Stop bit at the end of the sequential write operation and continue until the module responds to another operation.
3. 50 K write cycles at 70°C.

## I/O Timing for Squelch and Disable

Parameter	Symbol	Min	Max	Unit	Condition and Notes
Rx Squelch Assert Time	$t_{Rxsq,ON}$		0.080	ms	Note 1
Rx Squelch Deassert Time	$t_{Rxsq,OFF}$		0.080	ms	Note 2
Tx Squelch Assert Time	$t_{Txsq,ON}$		400	ms	Note 3
Tx Squelch Deassert Time	$t_{Txsq,OFF}$		400	ms	Note 4
Tx Disable Assert Time	$t_{Txdis,ON}$		100	ms	Note 5
Tx Disable Deassert Time	$t_{Txdis,OFF}$		400	ms	Note 6
Rx Output Disable Assert Time	$t_{Rxdis,ON}$		100	ms	Note 7
Rx Output Disable Deassert Time	$t_{Rxdis,OFF}$		100	ms	Note 8
Squelch Disable Assert Time	$t_{Sqdis,ON}$		100	ms	Note 9
Squelch Disable Deassert Time	$t_{Sqdis,OFF}$		100	ms	Note 10

### Notes:

1. Time from loss of Rx input signal until the squelched output condition is reached.
2. Time from resumption of Rx input signals until normal Rx output condition is reached.
3. Time from loss of Tx input signal until the squelched output condition is reached.
4. Time from resumption of Tx input signals until normal Tx output condition is reached.
5. Time from Tx Disable bit set (value = 1b) until optical output falls below 10% of nominal.
6. Time from Tx Disable bit cleared (value = 0b) until optical output rises above 90% of nominal. Measured from Stop bit low-to-high SDA transition.
7. Time from Rx Output Disable bit set (value = 1b) until Rx output falls below 10% of nominal.
8. Time from Rx Output Disable bit cleared (value = 0b) until Rx output rises above 90% of nominal.
9. This applies to Rx and Tx Squelch and is the time from bit set (value = 1b) until squelch functionality is disabled.
10. This applies to Rx and Tx Squelch and is the time from bit cleared (value = 0b) until squelch functionality is enabled.

## Memory Map

Tx Lower Page (1010 000x) – Required		
Byte	Type	Functions
0-6	RO	Tx Status: 0xA8 Presence, Flat/ Paging Memory Presence, Interrupt, Data Not Ready, Loss of Signal, Fault, Summary of Alarms
7-18	RO	Latched Tx Alarms: Loss of Signal, Fault, Per-channel Alarms (Power or Current High/Low), Device Alarms (Temp, Vcc3.3 or Vcc12)
22-27	RO	Module Monitors: Temp, Voltage
38-39	RO	Module Monitors: Elapsed Operating Time
40-41	RW	Module Control: Rate/Application Select
51	RW	Module Control: Tx Reset
52-67	RW	Tx Channel Control: Disables, Squelch, Polarity Flip, Margin, Equalization Control
95-106	RW	Masks for Alarms: Channel (LOS, Fault), Channel Internal (Power or Current High/Low) and Module (Temp, Voltage)
110-118	RW	Vendor Specific Area – Read/Write
119-126	RW	Password
127	RW	Upper Page Select Byte (00h or 01h or 02h)

Rx Lower Page (1010 100x) – Optional		
Byte	Type	Functions
0-6	RO	Rx Status: Flat/ Paging Memory, Interrupt, Data Not Ready, Loss of Signal, Fault, Summary of Alarms
7-18	RO	Latched Rx Alarms: Loss of Signal, Fault, Per-channel Alarms (Power or Current High/Low), Device Alarms (Temp, Vcc3.3 or Vcc12)
22-27	RO	Module Monitors: Temp, Voltage
38-39	RO	Module Monitors: Elapsed Operating Time
40-41	RW	Module Control: Rate/Application Select
51	RW	Module Control: Rx Reset
52-73	RW	Rx Channel Control: Disables, Squelch, Polarity Flip, Margin, Amplitude, Pre-emphasis Control
95-106	RW	Masks for Alarms: Channel (LOS, Fault), Channel Internal (Power High/Low) and Module (Temp, Voltage)
110-118	RW	Vendor Specific Area – Read/Write
119-126	RW	Password
127	RW	Upper Page Select Byte (00h or 01h or 02h)

Tx Upper Page 01h (Optional)		
Byte	Type	Functions
128-167	RO	Module Alarm Threshold Settings
168-179	RO	Channel Alarm Threshold Settings
180-181	RO	Checksum
182-229	RO	Per-Channel Monitors: Tx Bias Current and Light Output
230-255		Reserved – Vendor-Specific Tx Functions

Upper Page 00h (identical for Tx & Rx) Required		
Byte	Type	Functions
128-129	RO	Identifiers
130-146	RO	Device Description: Cable & Connector, Power Supplies, Max Case Temp, Min-Max Signal Rate, Laser Wavelength or Copper Attenuation, and Supported Functions
147	RO	Description: Device Technology
152-222	RO	Vendor Information: Name & OUI, PN & PN rev, Serial Number, Data Code, & Customer-specific Information
223	RO	Checksum on 128-222
224-255	RO	Vendor Specific Area – Read-only

Tx and/or Rx Upper Page 02h (Optional)		
Byte	Type	Functions
128-247	RW	User Writable EEPROM (120 B)
248-255		Reserved - Vendor Specific (8 B)

Rx Upper Page 01h (Optional)		
Byte	Type	Functions
128-167	RO	Module Alarm Threshold Settings
168-179	RO	Channel Alarm Threshold Settings
180-181	RO	Checksum
206-229	RO	Per-Channel Monitors: Rx Input Power
230-255		Reserved – Vendor-Specific Rx Functions

### Connector Orientation for 24 fiber MTP/MPO connector

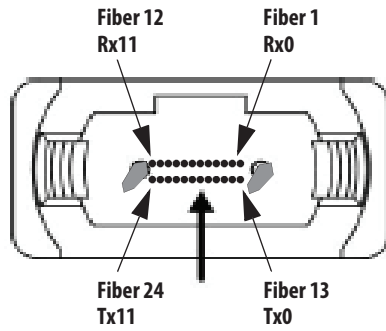


Figure 8. 24-fiber MPO Receptacle

Optical cables with 24-fiber MPO-style connectors on each end shall be built “Key up/Key down” so that the helix half-twist incurred when the cable is lugged into transceivers will correctly connect transmitter lanes to receiver lanes: lanes 0 to 0 and 11 to 11. MPO-style ‘male’ alignment pins are used in the receptacle and a “female” MPO-style connector shall be used on the cable connector.

### Recommended Power Supply Filter

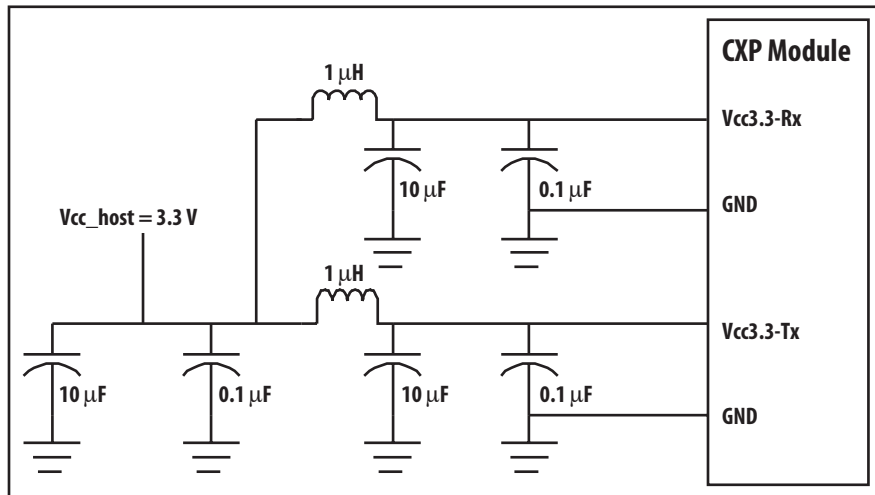
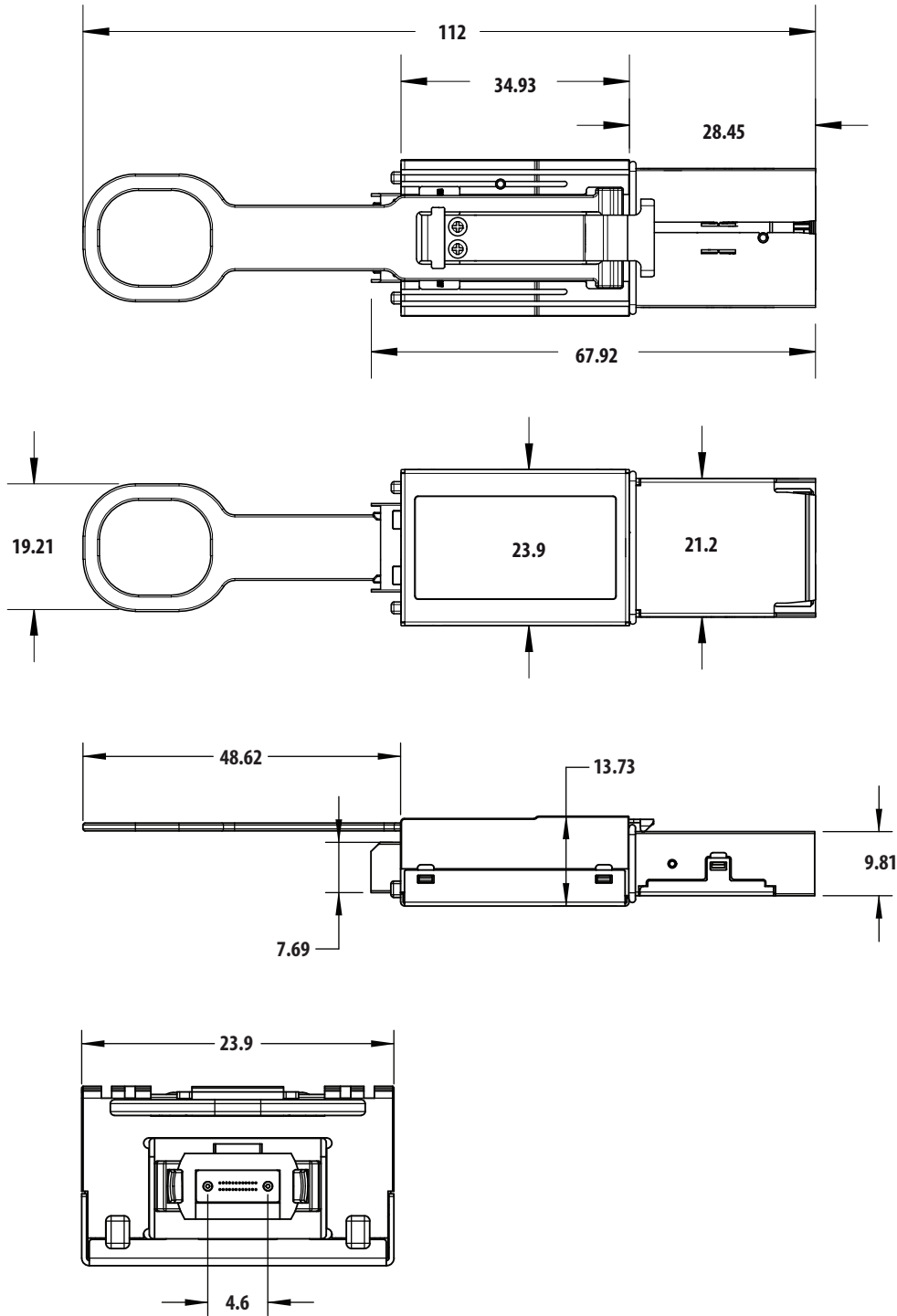


Figure 9. Recommended Power Supply Filter

## Mechanical Dimensions, Package Outline



All dimensions in millimeters

Figure 10. Transceiver package dimensions

## Host Board Connector

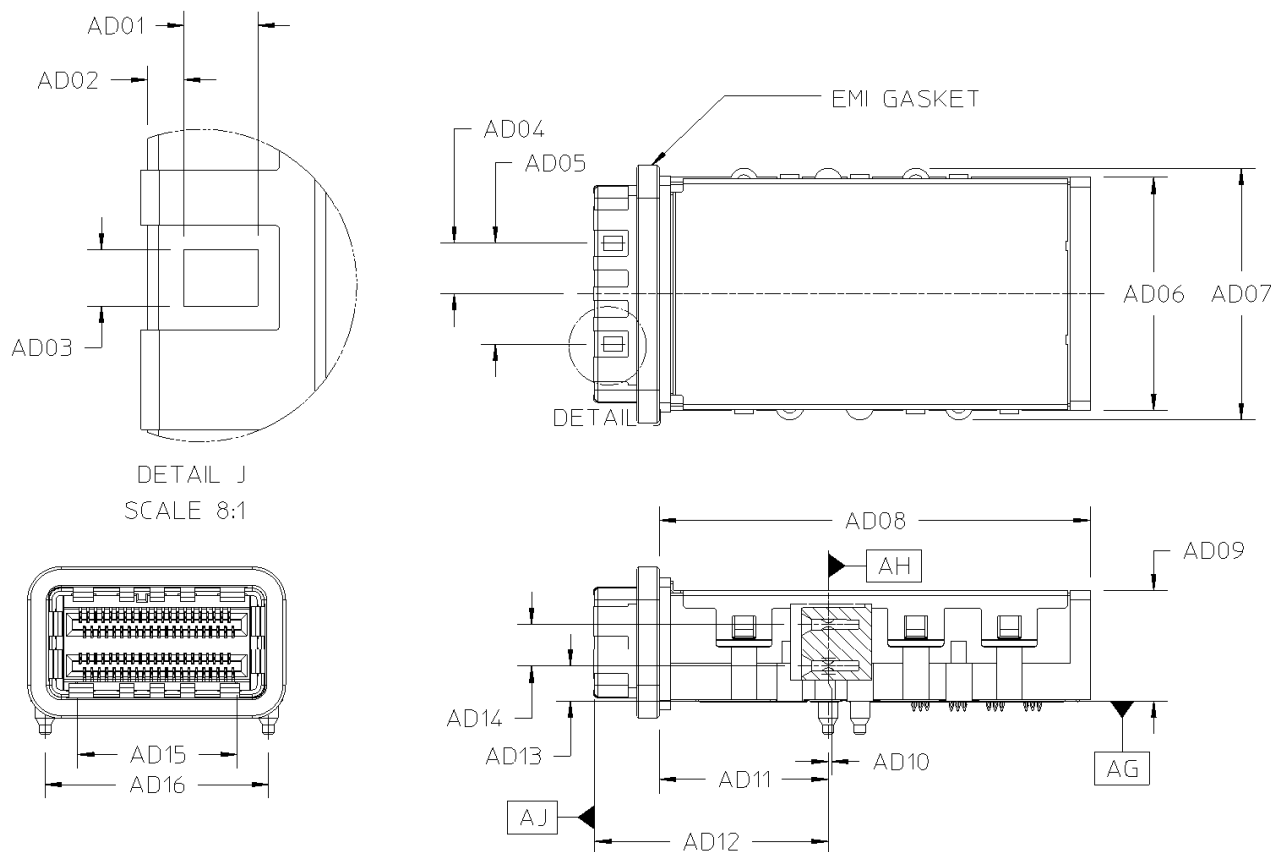


Figure 11. CXP host board connector dimensions (part 1 of 2)

ID	Description	Dim.	Tol. (±)	ID	Description	Dim.	Tol. (±)
AD01	Latch Hole Length	2.00	0.10	AD09	Shell Height	11.88	0.13
AD02	Latch Hole from Face	0.97	0.05	AD10	Locating Post Centerline to Centerline of Receptacle Co	0.05	0.05
AD03	Latch Hole Width	1.50	0.10	AD11	Locating Post to EMI Shell Base	18.06	0.13
AD04	Datum to Latch Hole	5.40	0.10	AD12	Locating Post to Face	25.06	0.08
AD05	Latch Hole to Hole	10.80	0.05	AD13	PCB to Lower Card Slot Centerline	3.75	0.10
AD06	Shell Width	25.05	0.25	AD14	Lower Card Slot to Upper Card Slot Centerline	4.50	0.10
AD07	Shell Width at screw attach features	27.00	0.25	AD15	Card Slot Rib to Rib	17.18	0.10
AD08	EMI Shell Base to Back	46.22	0.25	AD16	Peg Centerline to Peg Centerline	24.00	0.08

## Host Board Connector (con't)

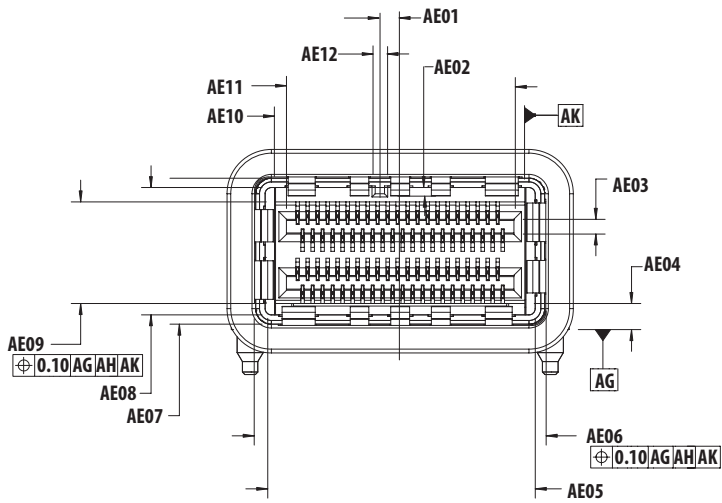


Figure 12. CXP host board connector dimensions (part 2 of 2)

ID	Description	Dim.	Tol. (±)	ID	Description	Dim.	Tol. (±)
AE01	Orientation Key Location	1.63	0.13	AE07	Snout Height	11.70	0.08
AE02	Orientation Key Location, Depth	20.75	Basic	AE08	Snout Opening Height	10.20	0.05
AE03	Card Slot Height	1.18	0.05	AE09	Receptacle Body Height	8.00	0.08
AE04	Datum to Bottom of Receptacle Housing	2.09	0.10	AE10	Receptacle Body Width	19.94	0.08
AE05	Snout Opening Width	21.60	0.05	AE11	Card Slot Width	18.20	0.05
AE06	Snout Width	23.10	0.08	AE12	Orientation Key Width	1.25	0.13

## Host PCB Footprint

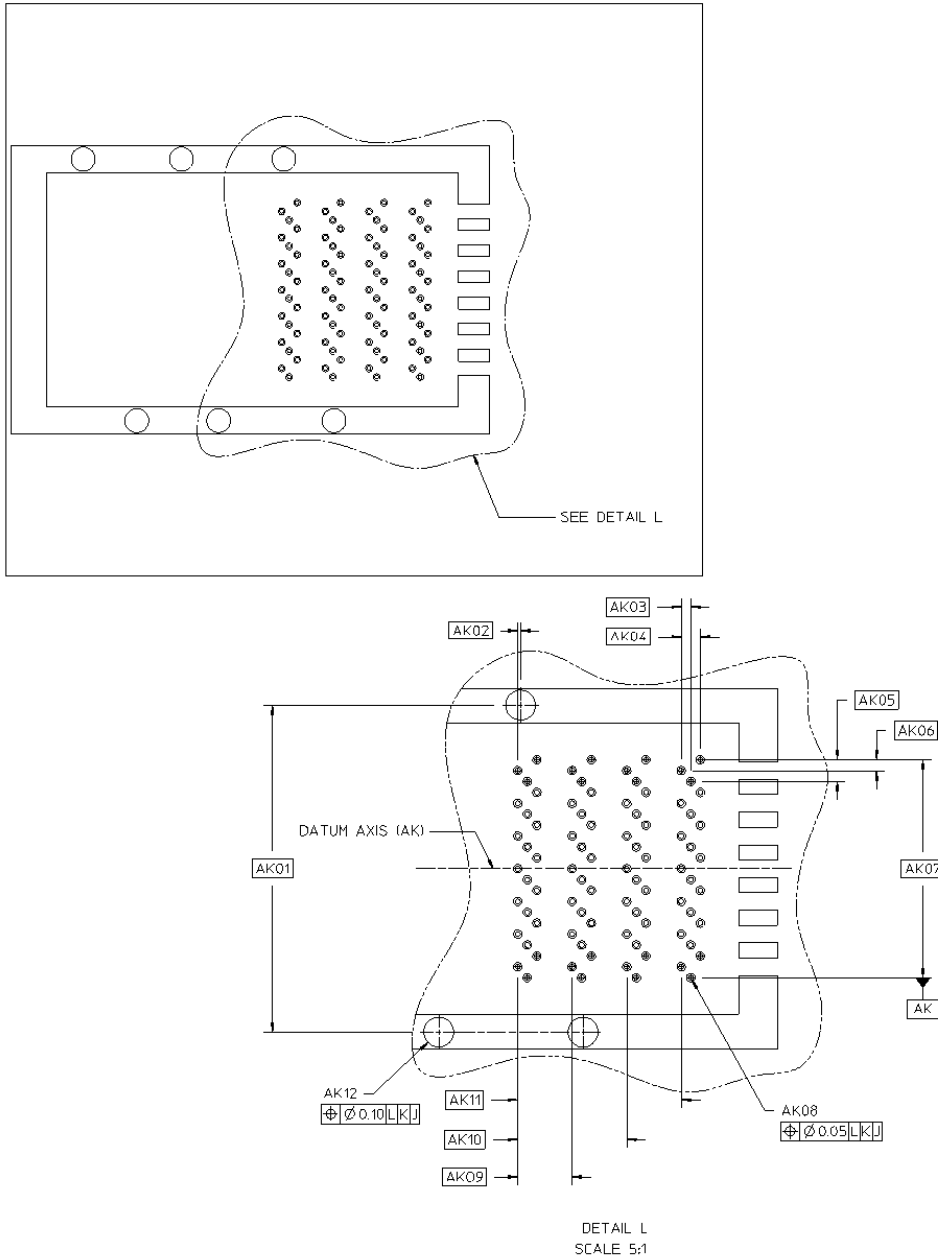


Figure 13. CXP host board connector footprint

ID	Description	Dim.	Tol. (±)	ID	Description	Dim.	Tol. (±)
AK01	Locating Hole to Locating Hole	24.00	0.05	AK07	First to Last Column	16.00	Basic
AK02	Locating Hole to First Row of Signal Holes	0.20	Basic	AK08	Contact Hole Diameter (Finished PTH)	0.37	0.05
AK03	First Row to Second Row of Signal Holes	0.70	Basic	AK09	Row A to Row B	4.00	Basic
AK04	First Row to Third Row of Signal Holes	1.40	Basic	AK10	Row A to Row C	8.00	Basic
AK05	Column to Column Pitch	1.60	Basic	AK11	Row A to Row D	12.00	Basic
AK06	Column to Column Pitch	0.80	Basic	AK12	Locating Hole Diameter (Finished PTH)	2.20	0.05



### CXP Cage and Bezel

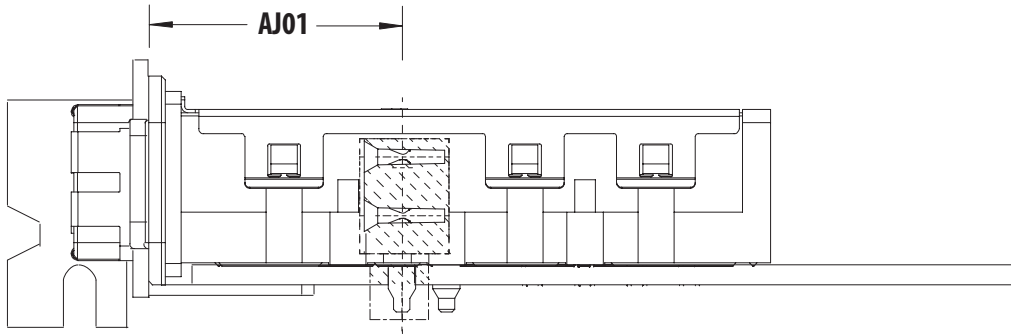


Figure 14. CXP cage-to-bezel dimensions

ID	Description	Dim.	Tol. (±)	ID	Description	Dim.	Tol. (±)
AJ01	Centerline of Receptacle Contacts to Base of EMI Shell	19.66	Basic	AJ02	-	-	-

### Bezel Opening

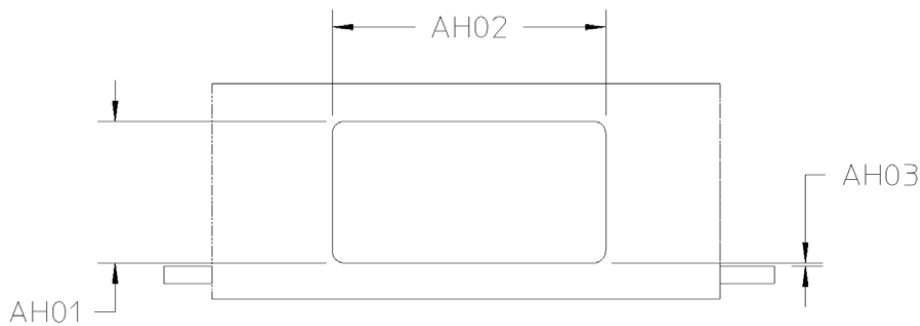


Figure 15. CXP bezel opening dimensions

ID	Description	Dim.	Tol. (±)	ID	Description	Dim.	Tol. (±)
AH01	Cutout Height	12.10	Basic	AH03	Bottom of Cutout to Peg	0.28	Basic
AH02	Cutout Length	23.50	Basic	AH04	-	-	-

### Heat Sink interface and Case Temperature Measurement point on the Connector Plug

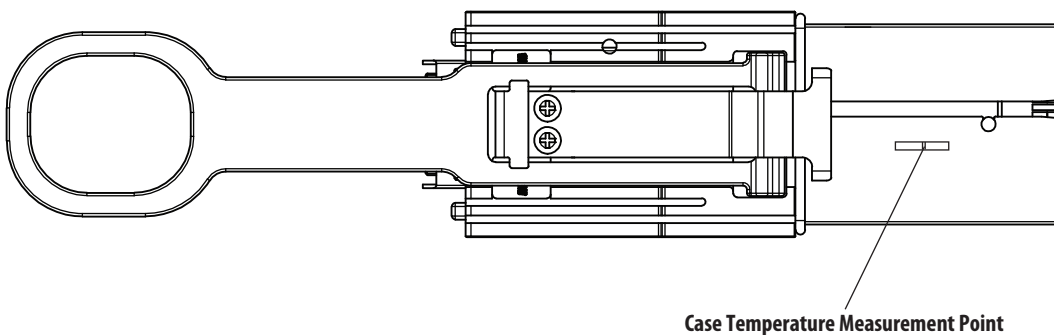


Figure 16. Case Temperature Measurement point

### Insertion, Extraction and Retention Forces for the CXP Transceiver

Symbol	Parameter	Min	Max	Unit	Comments
F <sub>i</sub>	CXP module insertion force		150	N	EIA 364-13
F <sub>w</sub>	CXP module extraction		50	N	EIA 364-13
F <sub>r</sub>	CXP module retention	90	170	N	Load pull, per EIA 364-38A No damage to transceiver below 90N
F <sub>rcl</sub>	Cage retention (latch strength)	180		N	No damage to latch below 180N
F <sub>rhb</sub>	Cage retention in host board	114		N	Force to be applied in a vertical direction, no damage to cage
N <sub>hc</sub>	Insertion / removal cycles, connector/receptacle	100		Cycles	Number of cycles for the connector and receptacle with multiple transceivers
N <sub>x</sub>	Insertion / removal cycles, CXP module	50		Cycles	Number of cycles for an individual module

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